

### **Product Description**

### Modified epoxy | 1 part | solvent-free | heat-curing

SMD adhesive

- Fast curing at low temperature
- Good shock resistance
- Short-term applicable (max.5 min) up to 270 °C

#### **Curing Properties**

This adhesive must be cured with heat. Typical curing temperatures are listed in the table below.

Temperatures	Time
100 °C	55 min
120 °C	20 min
150 °C	7 min

The curing times given are guidelines. They refer to rheological measurements according to PE-Norm 067. The heating times of the parts to be joined are not taken into account.

The final bond strength of the adhesive is achieved no sooner than 24 h after the bonded components are removed from the oven.



Technical Data			
Resin	Ероху		
Appearance	Pink		
Fluorescence	Blue		
Uncured Material			
Viscosity [mPas] (Brookfield LVT, 25 °C, Sp4/6rpm)	22,000 – 30,000		
PE-Norm 001	22,000 30,000		
Density [g/cm <sup>3</sup> ]	1.1		
PE-Norm 004			
Cured Material			
Hardness shore D	67		
PE-Norm 006	67		
Temperature resistance [°C]	-40 - 180		
Glass transition temperature - DSC [°C]	120		
PE-Norm 009	120		
Coefficient of thermal expansion [ppm/K] below Tg	50		
PE-Norm 017			
Coefficient of thermal expansion [ppm/K] above Tg	259		
PE-Norm 017			
Dielectric constant [10kHz]	3		
IEC 62631-2-1	3		
Volume resistivity [Ohm*cm]	8		
PE-Norm 040	0		
Young's modulus – Tensile test [MPa]	2100		
PE-Norm 056	2186		
Elongation at break [%]	<2		
PE-Norm 014	< 2		
Lap shear strength (steel/steel) [MPa]	17		
PE-Norm 13	1/		
Lap shear strength (stainless steel/stainlesssteel) [MPa]	29		
PE-Norm 13			
Lap shear strength (Al/Al) [MPa]	13		
PE-Norm 13			

### Transport/Storage/Shelf Life

Package type	Transport	Storage	Shelf life*
Syringe/Cartridge	0 °C – 10 °C	0 °C – 10 °C	At delivery min 4.5 months max. 9 months
Other packages			

\*Store in original, unopened containers!



#### Instructions for use

#### Surface preparation

The surfaces to be bonded should be free of dust, oil, grease, mold release, or other contaminants in order to obtain an optimal and reproducible bond. For cleaning we recommend the cleaner IP<sup>®</sup> from Panacol, or a solution of Isopropyl Alcohol at 90% or higher concentration. Substrates with low surface energy (e.g. polyethylene, polypropylene) must be pretreated in order to achieve sufficient adhesion.

#### Application

Our products are supplied ready to use. Depending on packaging they can be applied by hand directly from the container or by using compatible dispensing systems and automation. Many commercially available valve and controller options are available to ensure accurate and consistent adhesive dispensing. For assistance with dispensing and curing questions, please contact our Applications Engineering department. To obtain best results, the adhesive and substrates to be bonded may not be cold and should be allowed to warm to room temperature prior to processing. For safety information refer to our Material Safety Data Sheet (MSDS).

#### Storage

Store uncured product in its original, closed container in a dry location. Any material removed from the original container must not be returned to the container as it could be contaminated. Panacol cannot assume responsibility for products that were improperly stored, contaminated, or repackaged into other containers.

#### Handling and Clean-up

For safe handling information, consult this product's Material Safety Data Sheet (MSDS) prior to use. Uncured material may be wiped away from surfaces with organic solvents. Do not use solvents to remove material from eyes or skin!



#### Disclaimer

The product is free of heavy metals, PFOS and Phthalates and is conform to the current EU-Directive RoHS.

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Contact

Panacol-Elosol GmbH Stierstädter Straße 4 61449 Steinbach Germany Phone: +49 6171 6202-0 Mail: info@panacol.de www.panacol.com Panacol-USA, Inc. 142 Industrial Lane Torrington CT 06790 USA Phone: +1 860-738-7449 Mail: info@panacol-usa.com www.panacol-usa.com Panacol-Korea Co., Ltd. #707, Kranz Techno, 388 Dunchon-daero Junwon-gu, Seongnam Gyeonggi-do, 13403 KOREA Phone: +82 31 749 1701 Mail: info@panacol-korea.com www.panacol-korea.com Eleco Panacol – EFD 125, av Louis Roche Z.A. des Basses Noëls 92238 Gennevilliers Cdx FRANCE Tél.: +33 (0)1 47 92 41 80 Mail: eleco@eleco-panacol.fr www.eleco-panacol.fr

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